

ABSTRACT

A heat dissipating device includes a retention module (20) around an electronic component (15), a heat sink (30) attached to the retention module, and a fan (90). The heat sink includes a plurality of fins (62, 64, 66, 68) and spacers (52) interleaved between the fins, two heat pipes (80) sequentially extending through lower portions of the fins, the spacers and upper portions of the fins to bond the fins and the spacers together. Each spacer includes a flat bottom face for contacting the electronic component, and an arcuate top face. The fins includes two outer fins, and a plurality of inner fins each defining a cutout (62a, 64a) cooperatively defining a chamber between the outer fins. The chamber and the arcuate spacers facilitate cooling air from the fan to blow to opposite sides of the heat sink thereby improving heat dissipation efficiency of the heat sink.